



# Product Intro

Big Dipper

2024

# Big Dipper Infinite/Infinite AI



Big Dipper Infinite/Infinite AI



Big Dipper Micro Led TV



# Specification



series	COB					
Pixel Pitch	P0.625	P0.78	P0.93	P1.25	P1.56	P1.87
COB Module	150*168.75mm					
COB Module Resolution	240*270	192*216	160*180	120*135	96*108	80*90
Cabinet Dimension	600*337.5*39.5mm		600*675*39.5mm		/600*337.5*39.5mm	
Cabinet Resolution	960*540	768*432	640*720/640*360	480*540/480*270	384*432/384*216	320*360/320*180
Grayscale	18-20bit+					
Brightness	600nit/1000nit (after calibration)					
Contrast Ratio	20,000:1					
Refresh Rate	3,840HZ					
Viewing Angle	170° (H/V)					
Power Input	AC100-240V(50/60Hz)					
Power Consumption(Max.)	≈130w/cabinet(600*675mm)/≈65w/cabinet(600*337.5mm), ≈325w/m <sup>2</sup> (600nit)					
Power Consumption(Ave.)	≈20w/cabinet(600*337.5mm)/≈40w/cabinet(600*675mm), ≈100w/m <sup>2</sup> (600nit)					
Certification	CCC/CE/Energy-saving/RoHS/ETL/UL/CB/EMC					

# Display Performance



## Wide Color Gamut

Big Dipper COB LED supports a wide color gamut, covering **98%** of the **DCI-P3** color space.

Big Dipper



Other



## Advanced HDR Performance

Big Dipper COB LED features cutting-edge HDR technology, supporting up to **22-bit+** color depth for unparalleled image realism and depth





# Big Dipper COB Advantages



## High Protection Level – IP54 Rating

Ensures dust and splash resistance, suitable for various environments.

## Panel Hardness – 4H

Offers excellent resistance to scratches and abrasions, maintaining clear visibility.

## Water Washable Surface

Easy to clean without damaging the screen, ensuring hygiene and low maintenance.

## Anti-Static Properties

prevents static electricity damage, enhancing longevity.

## Oxidation Resistance

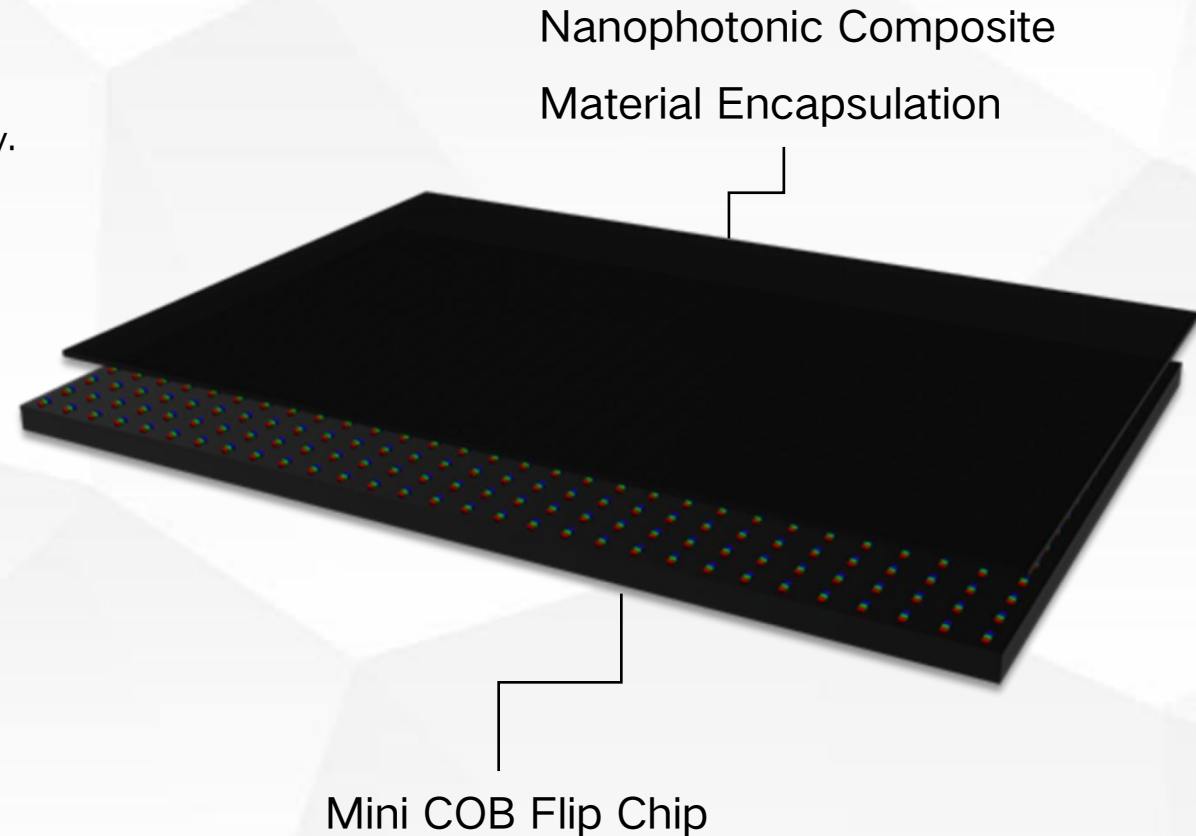
Prevents rust and corrosion

## Anti-Glare Coating

Minimizes reflection and glare, providing better visibility under bright conditions.

## Impact Resistant

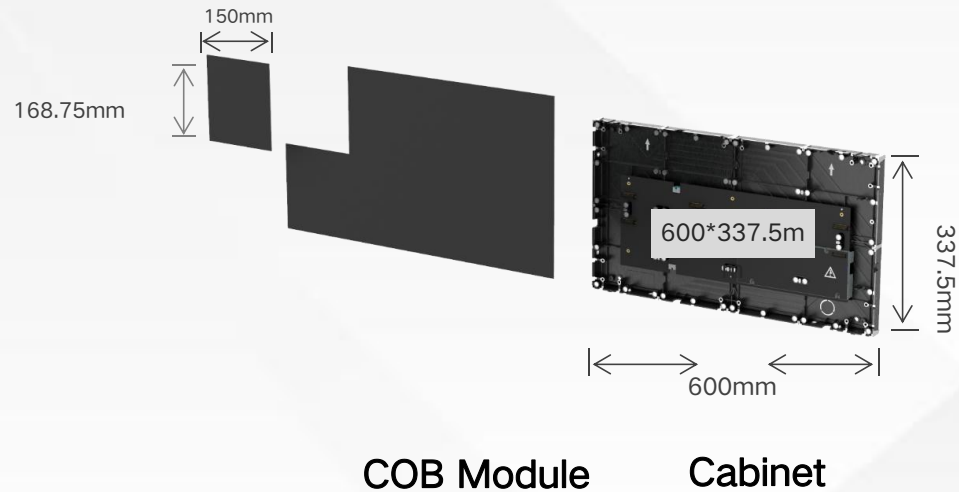
Designed to withstand minor impacts, reducing the risk of damage from accidental bumps.



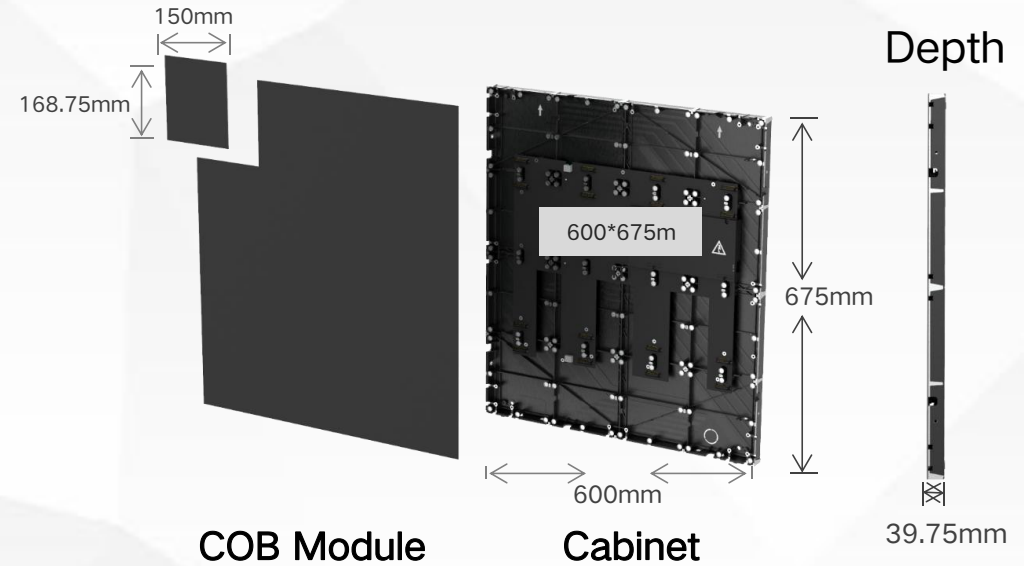
# Big Dipper Infinite/Infinite AI Structure



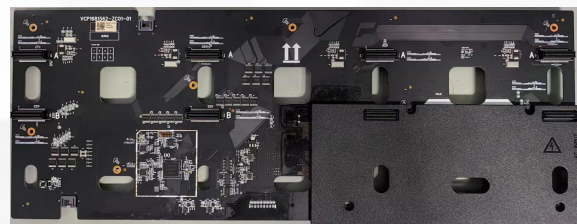
### Cabinet size 1



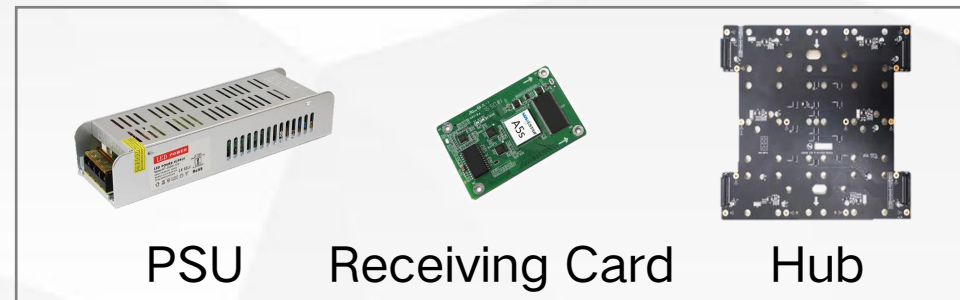
### Cabinet size 2



### 3 in 1 Board



3 in 1 board



# Big Dipper Micro Led TV series



- ✓ Flip Chip COB technology
- ✓ Google & Roku
- ✓ Plug & Play
- ✓ Seamless Alignment
- ✓ Contrast Ratio: 20,000 : 1
- ✓ HDR
- ✓ Built-in Hi-Fi Speaker

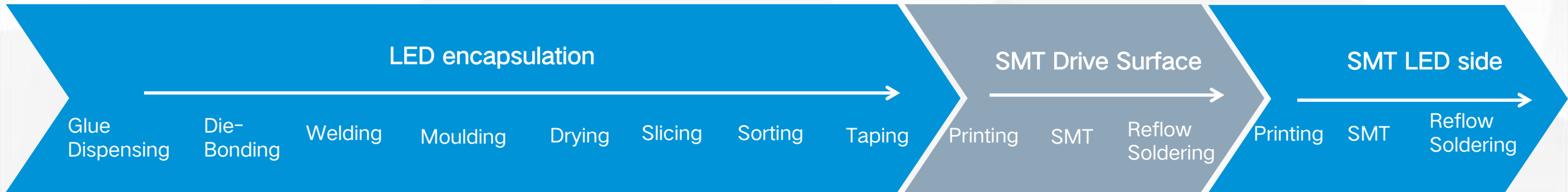




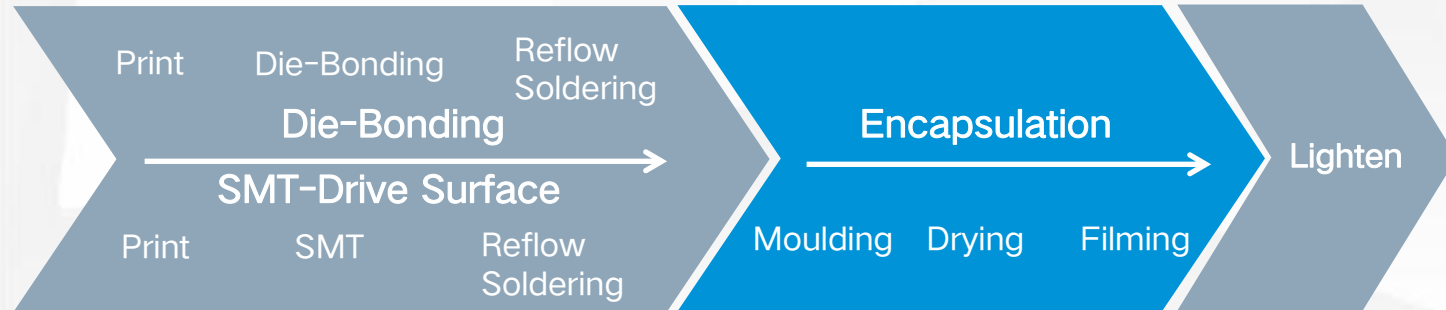
# COB VS SMD

processing route --> Stability

## SMD



## COB



**COB is higher stability** due to **shorter** processing route without complicated encapsulation process as SMD did.



# COB VS SMD



	Technical	SMD	COB
Reliability	LED Failure Rate	200PPM	5PPM
	Robustness	Fragile	≥4H
	Moisture-Proof	No	IP54 front
	Low power Consumption (white balance)	≥55°C, ≥5000w/sq.m	≤45°C, ≤370w/sq.m
Display performance	Contrast Ratio	3,000:1	20,000:1
	Color Garmut	NTSC ≤100%	DCI-P3 98%, NTSC ≥117%
	Grainy	Yes	No
	View angle	±140°	±160°
	Moire Pattern	Obviously	Reduced significantly

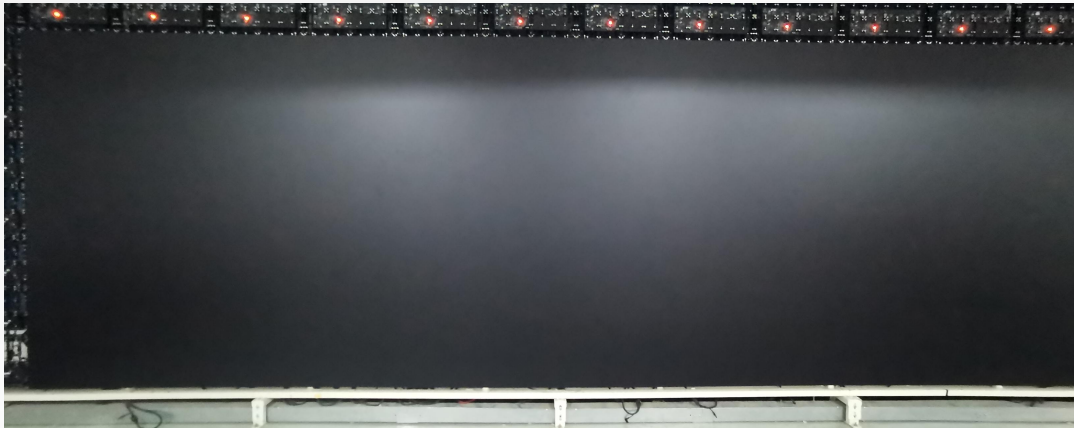
# Big Dipper COB Advantages



## Black Uniformity

No batches or Sorting concerns for every shipment

Front View



Side View



Close Up Comparison

SMD 1.2 VS COB 1.2



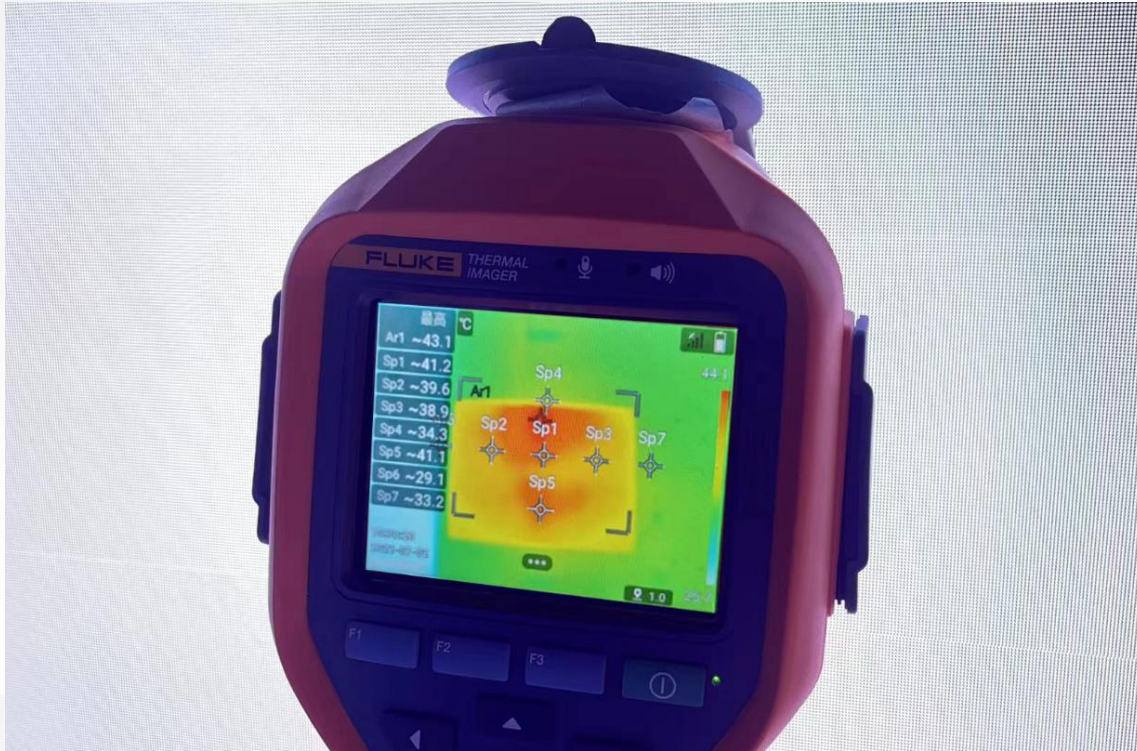




# Electrical Advantages

## Advanced Heat Management

White balance Temp.  $\leq 45^{\circ}\text{C}$  at room temp.



## Energy Efficiency

$\leq 75\text{w/cabinet}$

$\leq 370\text{w/sq.m}$



# Technical Advantages



	Flip-Chip	Formal
Chip section view		
COB section view		
Gerber		
Features	<ul style="list-style-type: none"> <li>✓ Lower power consumption, lower surface temp.</li> <li>✓ Sealed Chips, anti humidity</li> <li>✓ The electrode has no migration leakage</li> <li>✓ Higher Reliability due to wider GAP</li> </ul>	<ul style="list-style-type: none"> <li>• Poor Welding/wire break/current leakage</li> <li>• Higher thermal resistance</li> <li>• Vulnerable lamps</li> <li>• Frequent maintenance</li> </ul>



# Display Performance

## Long-term Color Consistency

Die-bonding with fixed Bin No., and fixed wavelength, calibration before shipment.

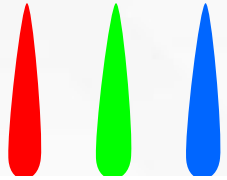
Die-bonding with fixed Bin No.

New Chip-mixing process

Dot to dot calibration

Mini COB

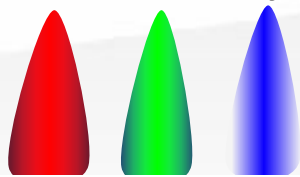
High Color Purity



R:625-630nm  
G:533-535nm  
B:465-467nm  
DCI-BT2020

SMD

Low Color Purity



R:620-630nm  
G:520-530nm  
B:465-475nm

